

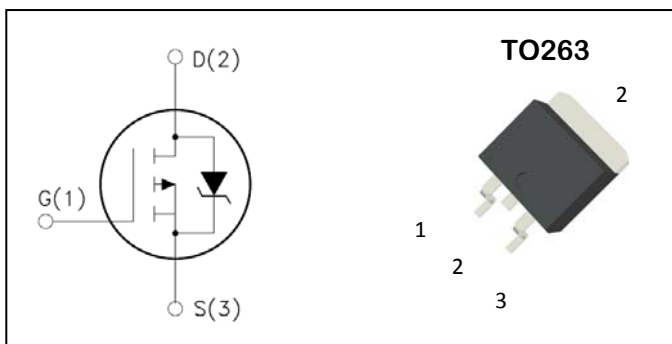
## P-Channel Logic Level Enhancement Mode Field Effect Transistor

### PRODUCT SUMMARY

$V_{DSS}$	$I_D$	$R_{DS(ON)}$ (m $\Omega$ )
-60V	-167A	4.7m $\Omega$

### Features:

- High Current Rating
- Super Low  $R_{DS(ON)}$
- 100% EAS Guaranteed
- Advanced Trench technology
- Lead-Free, RoHS Compliant



### Description:

The AM160P06G series MOSFETs is a new technology, which combines an innovative super junction technology and advance process. This new technology achieves low  $R_{ds(on)}$ , energy saving, high reliability and uniformity, superior power density and space saving.

### Absolute Maximum Ratings ( $T_A = 25^\circ\text{C}$ unless otherwise specified )

Symbol	Parameter	Ratings	Unit
<b>Common Ratings</b>			
$V_{DSS}$	Drain-Source Voltage	-60	V
$V_{GSS}$	Gate-Source Voltage	$\pm 20$	
$T_J$	Maximum Junction Temperature	150	$^\circ\text{C}$
$T_{STG}$	Storage Temperature Range	-55 to 150	$^\circ\text{C}$
$I_S$	Diode Continuous Forward Current <sup>(1,6)</sup>	$T_C = 25^\circ\text{C}$ -167	A
<b>Mounted on Large Heat Sink</b>			
$I_{DM}$	300 $\mu\text{s}$ Pulse Drain Current Tested <sup>(2)</sup>	$T_C = 25^\circ\text{C}$ -340	A
$I_D$	Continuous Drain Current <sup>(1)</sup>	$T_C = 25^\circ\text{C}$ -167	A
		$T_C = 100^\circ\text{C}$ -105	A
$P_D$	Maximum Power Dissipation <sup>(4)</sup>	$T_C = 25^\circ\text{C}$ 208	W
	Maximum Power Dissipation <sup>(4)</sup>	$T_A = 25^\circ\text{C}$ 2	W

### Thermal Characteristics

Symbol	Parameter	Ratings	Unit
$R_{thJC}$	Thermal resistance junction-case max <sup>(1)</sup>	0.6	$^\circ\text{C}/\text{W}$
$R_{thJA}$	Thermal resistance junction-ambient max <sup>(1)</sup>	62	$^\circ\text{C}/\text{W}$

## Electrical Characteristics (TA=25°C Unless Otherwise Noted)

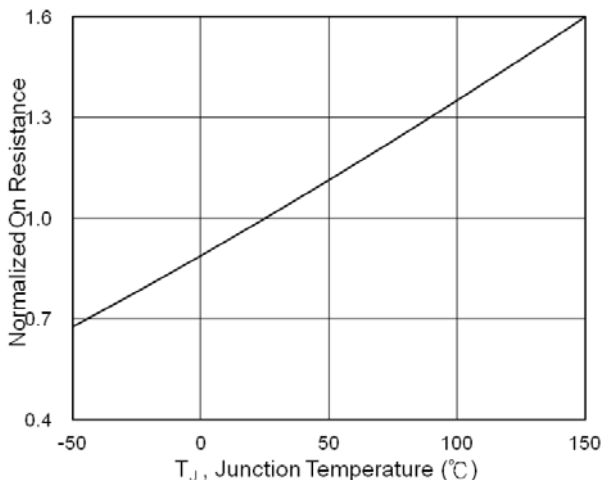
Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
<b>On/off Characteristics</b>						
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V, I <sub>DS</sub> =-250uA	-60	--	--	V
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> =-60V, V <sub>GS</sub> =0V T <sub>J</sub> =25°C	--	--	1	uA
		V <sub>DS</sub> =-60V, V <sub>GS</sub> =0V T <sub>J</sub> =55°C	--	--	5	
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>DS</sub> =-250A	-1.2		-2.5	V
I <sub>GSS</sub>	Gate Leakage Current	V <sub>GS</sub> =±20V, V <sub>DS</sub> =0V	--	--	±100	nA
R <sub>DS(ON)</sub>	Drain-Source On-state Resistance <sup>(2)</sup>	V <sub>GS</sub> = -10V, I <sub>DS</sub> =30A	--	3.7	4.7	mΩ
<b>Dynamic Characteristics</b>						
C <sub>iss</sub>	Input Capacitance	V <sub>GS</sub> =0V, V <sub>DS</sub> = -15V, Frequency=1MHz	--	24570	--	pF
C <sub>oss</sub>	Output Capacitance					
C <sub>rss</sub>	Reverse Transfer Capacitance					
<b>Switching Characteristics</b>						
t <sub>d(ON)</sub>	Turn-on Delay Time	V <sub>DS</sub> =-30V, I <sub>D</sub> = -30A, V <sub>GS</sub> = -10V, R <sub>GEN</sub> =3.3 Ω	--	39.2	--	ns
t <sub>r</sub>	Turn-on Rise Time					
t <sub>d(OFF)</sub>	Turn-off Delay Time					
t <sub>f</sub>	Turn-off Fall Time					
Q <sub>g</sub>	Total Gate Charge	V <sub>DS</sub> =-48V, V <sub>GS</sub> = -10V, I <sub>DS</sub> =-30A	--	368	--	nC
Q <sub>gs</sub>	Gate-Source Charge					
Q <sub>gd</sub>	Gate-Drain Charge					
EAS	Single Pulse Avalanche Energy <sup>(5)</sup>	V <sub>DD</sub> =-50V , L=1mH , I <sub>AS</sub> =-30A	450	--	--	mJ
<b>Diode Characteristics</b>						
V <sub>SD</sub>	Diode Forward Voltage <sup>(2)</sup>	I <sub>SD</sub> = -30A, V <sub>GS</sub> = 0	--	--	-1.2	V
t <sub>rr</sub>	Reverse Recovery Time	I <sub>SD</sub> =-30A, dI <sub>SD</sub> /dt=100A/μs	--	36.4	--	ns
q <sub>rr</sub>	Reverse Recovery Charge		--	32.2	--	nC

### NOTES:

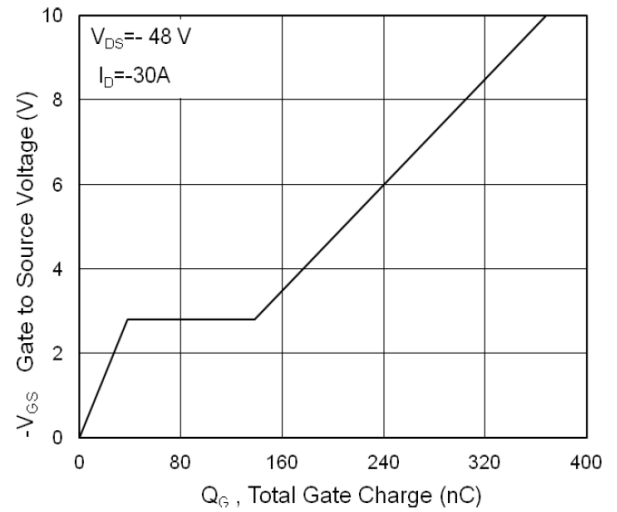
- 1.The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width ≤ 300us , duty cycle ≤ 2%
- 3.The EAS data shows Max. rating . The test condition is V<sub>DD</sub>=-50V, V<sub>GS</sub>=-10V, L=1mH, I<sub>AS</sub>=-40A
- 4.The power dissipation is limited by 150°C junction temperature
- 5.The Min. value is 100% EAS tested guarantee.
- 6.The data is theoretically the same as I<sub>D</sub> and I<sub>DM</sub> , in real applications , should be limited by total power dissipation.

## Typical Performance Characteristics

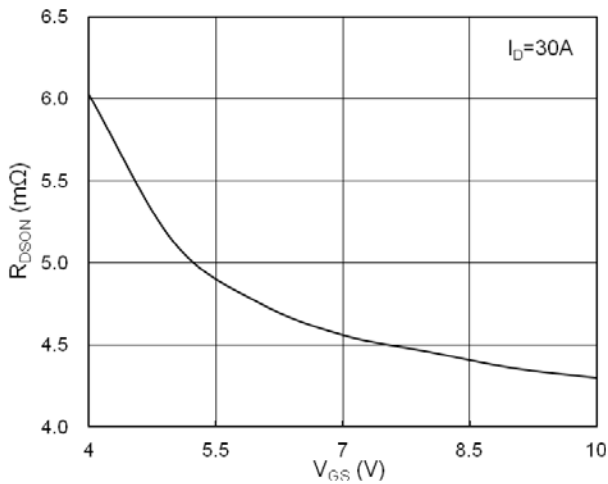
**Figure 1: Normalized  $R_{DS(on)}$  v.s  $T_J$**



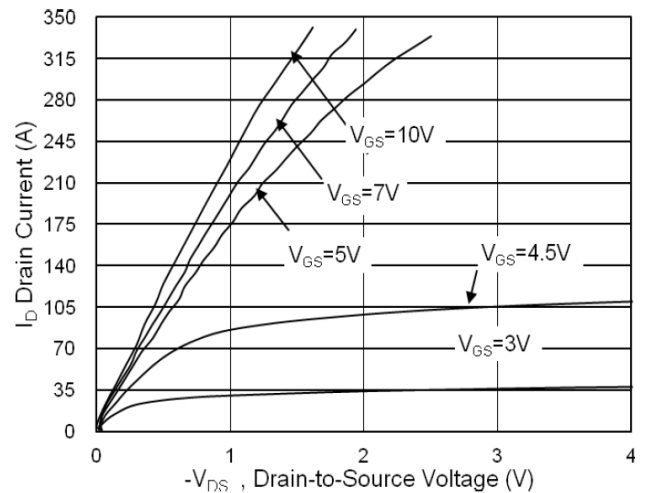
**Figure 2: Gate-Charge Characteristics**



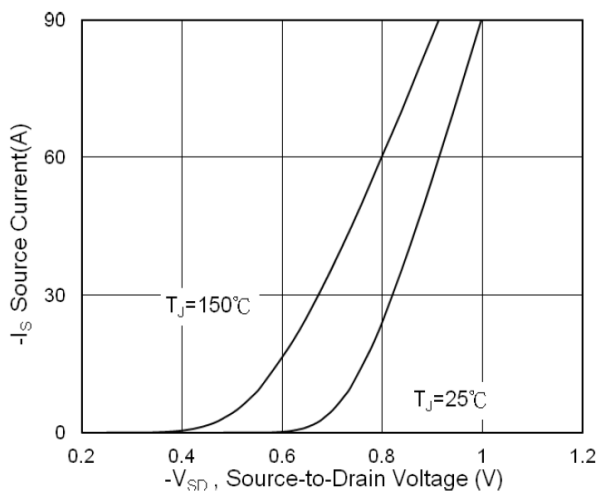
**Figure 3: On-Resistance v.s Gate-Source**



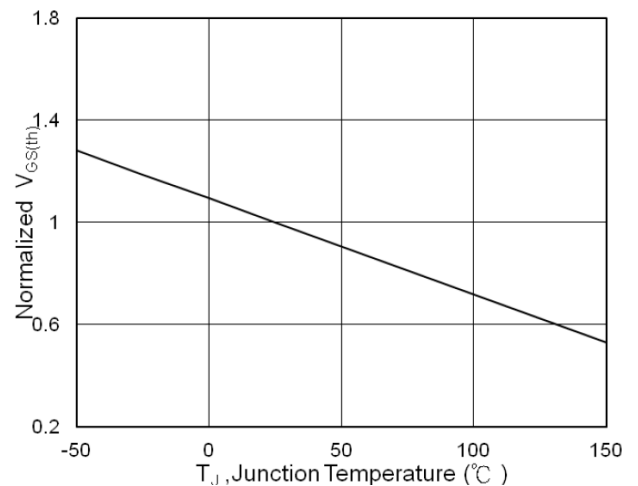
**Figure 4: Typical Output Characteristics**



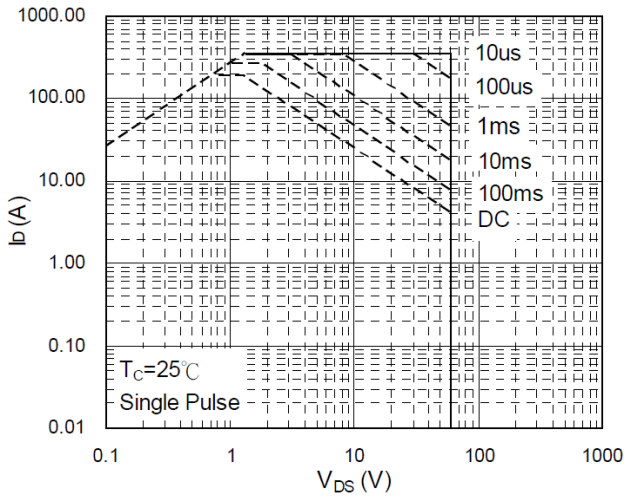
**Figure 5: Normalized  $V_{GS(th)}$  v.s  $T_J$**



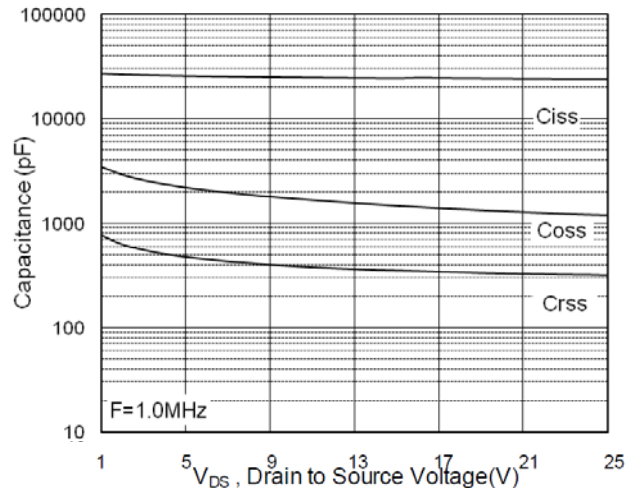
**Figure 6: Drain-source on-state resistance**



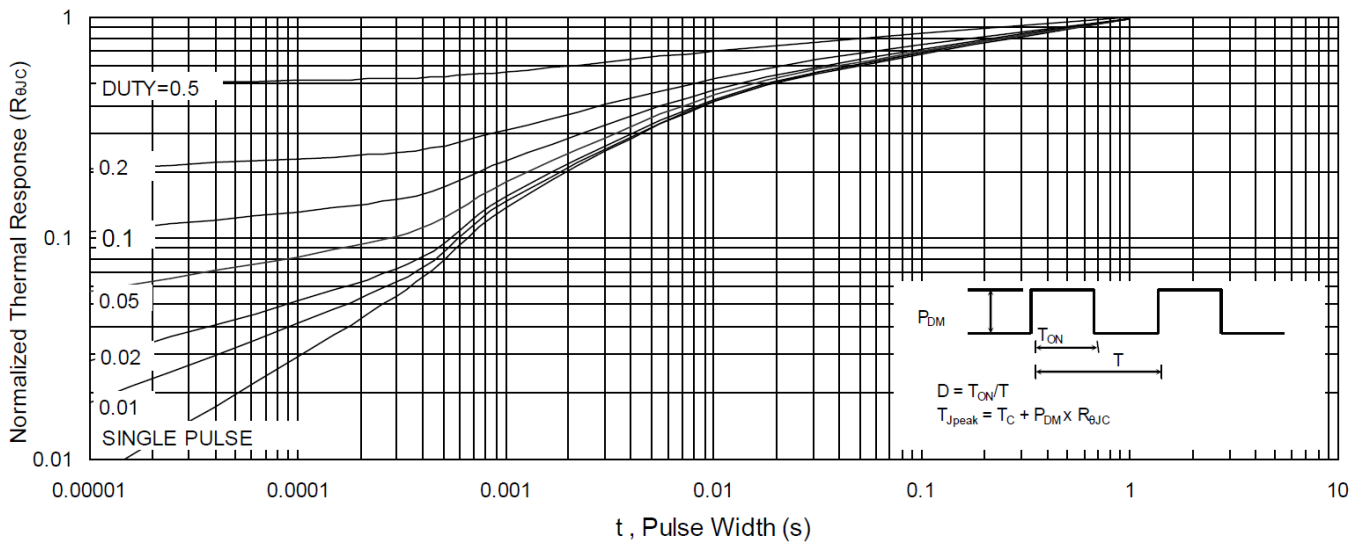
**Figure 7: Safe Operating Area**



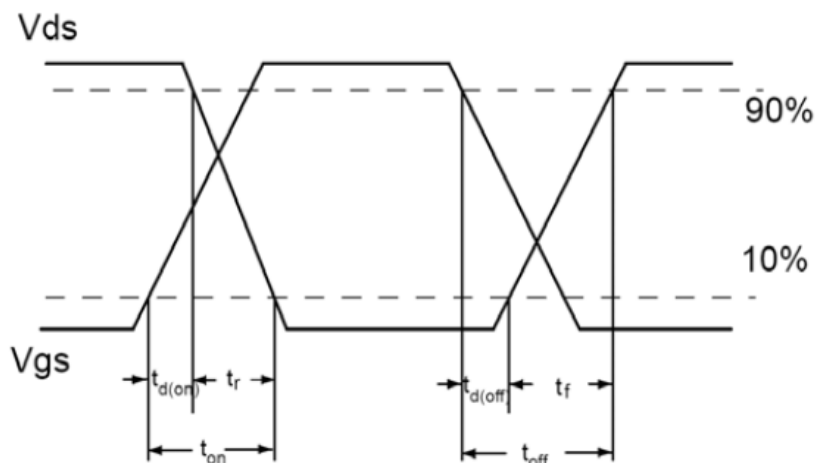
**Figure 8: Capacitance**



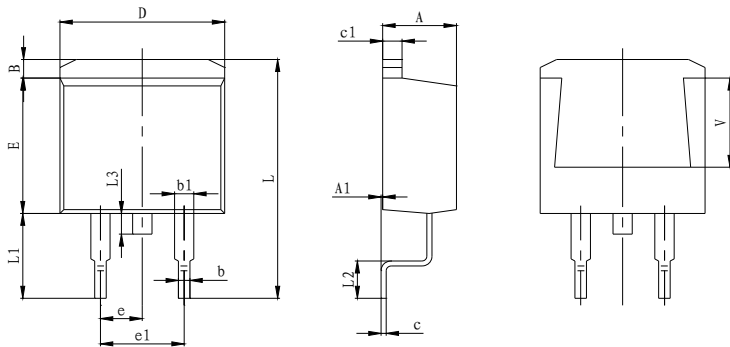
**Figure 9: Normalized Maximum Transient Thermal Impedance**



**Switch Waveforms:**



**PACKAGE MECHANICAL DATA**  
**TO-263-2 Package Dimension**



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	4.470	4.670	0.176	0.184
A1	0.000	0.150	0.000	0.006
B	1.170	1.370	0.046	0.054
b	0.710	0.910	0.028	0.036
b1	1.170	1.370	0.046	0.054
c	0.310	0.530	0.012	0.021
c1	1.170	1.370	0.046	0.054
D	10.010	10.310	0.394	0.406
E	8.500	8.900	0.335	0.350
e	2.540 TYP		0.100 TYP	
e1	4.980	5.180	0.196	0.204
L	15.050	15.450	0.593	0.608
L1	5.080	5.480	0.200	0.216
L2	2.340	2.740	0.092	0.108
L3	1.300	1.700	0.051	0.067
V	5.600 REF		0.220 REF	

**Ordering information**

Part number	Package	Marking	Packing	Quantity
ADM160P06G	TO-263-2	ADM160P06G	Tube	50pcs
			Embossed tape	800pcs